

# N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
30	0.0045 at V <sub>GS</sub> = 10 V	40	26.5 nC		
30	0.0060 at V <sub>GS</sub> = 4.5 V	33.3	20.5 110		

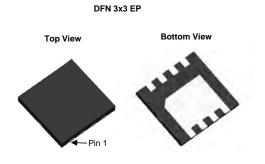
#### **FEATURES**

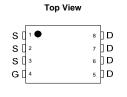
- · Halogen-free
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

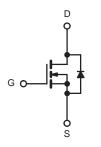


#### **APPLICATIONS**

- DC/DC Conversion
  - Low-Side Switch
- Notebook PC
- Gaming







N-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	30	V		
Gate-Source Voltage		V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		40		
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C	-	32.6		
Continuous Diam Current (1) = 130 °C)	T <sub>A</sub> = 25 °C	l <sub>D</sub>	31.5 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		27.1 <sup>b, c</sup>	Α Α	
Pulsed Drain Current		I <sub>DM</sub>	70	A	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		5.4		
	T <sub>A</sub> = 25 °C	ls ===	2.7 <sup>b, c</sup>		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	40		
Avalanche Energy	L = 0.111111	E <sub>AS</sub>	80	mJ	
	T <sub>C</sub> = 25 °C		6.0		
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	P <sub>D</sub>	3.3	w	
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	1 'D	3.0 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C	1	1.9 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	33	42	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	16	21	C/ V V	

- a. Based on  $T_C$  = 25 °C. b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 85 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	30			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	$V_{DS}/T_J$ $I_D = 250 \text{ µA}$		27		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 5.6		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	1.5		3.0	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zone Cote Valta de Brain Comment	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	1		1	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10 µ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A		0.0045		Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A		0.0060		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A		75		S
Dynamic <sup>b</sup>				1		
Input Capacitance	C <sub>iss</sub>			2545		pF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz		450		
Reverse Transfer Capacitance	C <sub>rss</sub>	1		140		
Total Cata Chausa		V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		62		
Total Gate Charge				26.5		0
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		8.5		nC
Gate-Drain Charge	$Q_{gd}$	]		7.3		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.2	1.1	2.2	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			35	60	
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		16	30	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		48	85	
Fall Time	t <sub>f</sub>	1		16	30	
Turn-On Delay Time	t <sub>d(on)</sub>			18	35	ns -
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		8	16	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		41	75	
Fall Time	t <sub>f</sub>	]		8	18	
Drain-Source Body Diode Characteristi	cs					
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			5.4	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				70	А
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 3 A		0.72	1.1	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			33	65	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 40 4 41/44 400 4/15 7 0500		27	54	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		17		
Reverse Recovery Rise Time	t <sub>b</sub>			16		ns

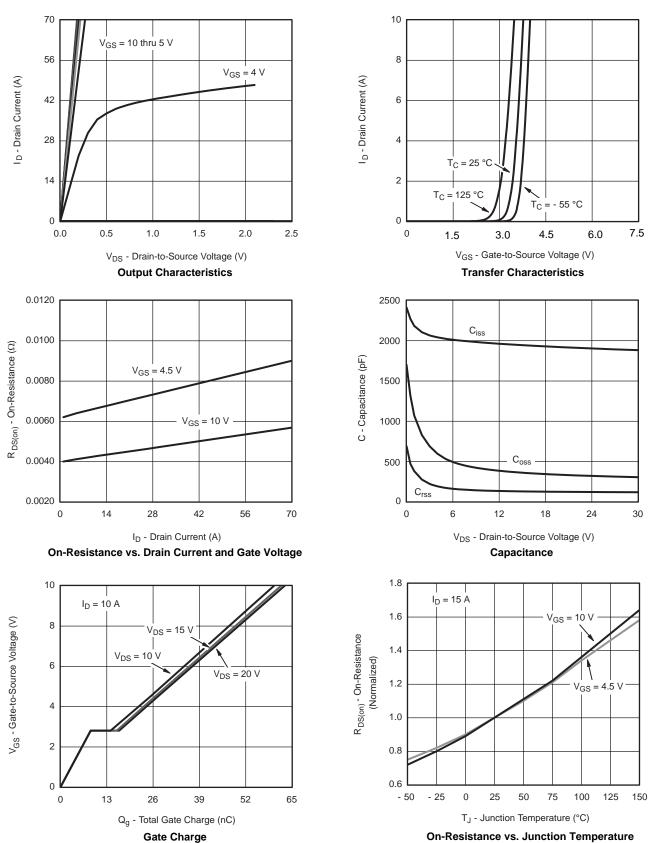
#### Notes:

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

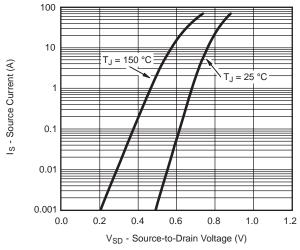


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

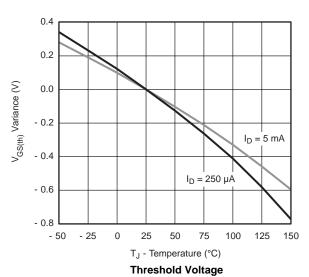




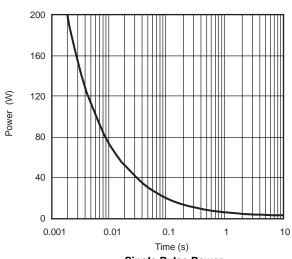
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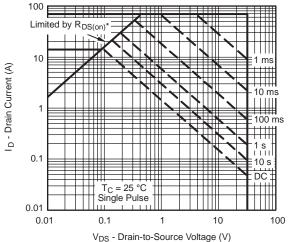
#### Source-Drain Diode Forward Voltage



0.025  $I_D = 15 \text{ A}$ 0.020 R<sub>DS(on)</sub> - On-Resistance (Ω) 0.015 0.010 T<sub>J</sub> = 125 °C 0.005  $T_J = 25^{\circ}C$ 0.000 2 3 4 5 0 6 8 10



Single Pulse Power

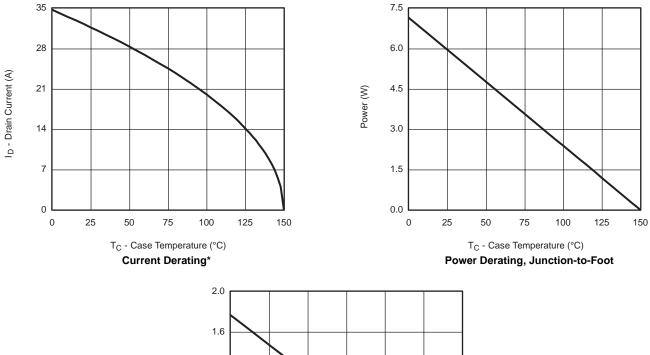


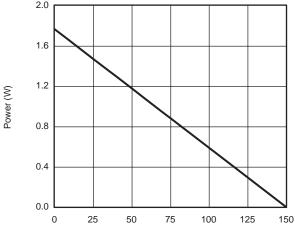
\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified

Safe Operating Area, Junction-to-Ambient



### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





T<sub>A</sub> - Ambient Temperature (°C)

Power, Junction-to-Ambient

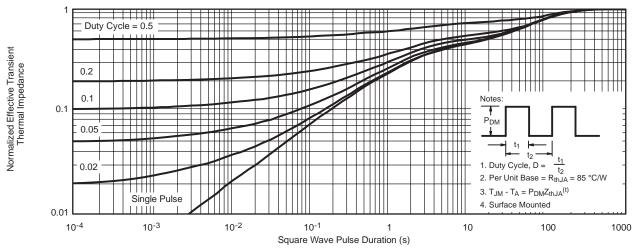
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limit.

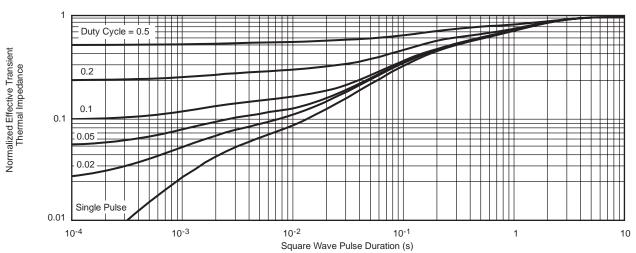
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package



### TYPICAL CHARACTERISTICS 25 C, unless otherwise noted

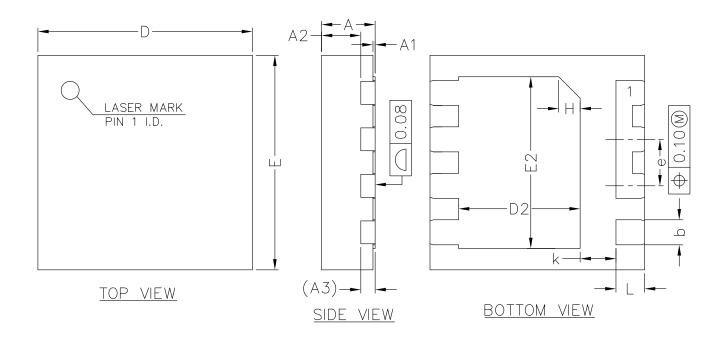


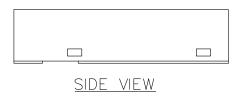
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot







COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX	
Α	0.70	0.75	0.80	
A1	0.00	0.02	0.05	
A2	0.50	0.55	0.60	
А3	0.20REF			
Ь	0.30	0.35	0.40	
D	2.90	3.00	3.10	
E	2.90	3.00	3.10	
D2	1.60	1.70	1.80	
E2	2.30	2.40	2.50	
е	0.55	0.65	0.75	
K	0.40	0.50	0.60	
L	0.35	0.40	0.45	



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